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Abstract of the Disclosure

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A position sensor designed in the form of a Hall sensor with an elongated circuit substrate (32) in the form of a molded interconnect device (MID) which includes an elongated support element consisting of injection molded plastic material, which at its front end side (37) has a support face (36), which is so fitted with a sensor element constituted by a Hall plate (27) or comprising a Hall plate (27) that the plane of the Hall plate (27) is perpendicular to the longitudinal axis of the circuit substrate (32). The sensor element (26) is electrically contacted by means of printed wiring (35), such printed wiring being constituted by a structured metal layer applied to the support element (34).

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Figure 4

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